

ARC-SAFE: Accelerated Response Semiconducting Contactors and Surge Attenuation For DC Electrical Systems

Sandia National Laboratories

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Opportunity

- Medium Voltage DC systems lack suitable circuit breaker (CB) technologies – limits system performance and adoption
 - Solar and Wind power generation growing rapidly
 - Electric ship and rail power management, electric vehicles



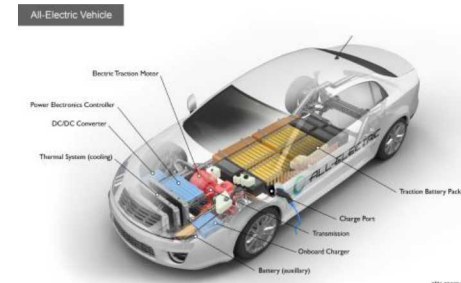
<http://www.industrytap.com/wp-content/uploads/2013/02/US-Electrical-Grid.jpg>



<https://www.nrel.gov/wind/grid-integration.html>



<https://www.navsea.navy.mil/Home/Team-Ships/PEO-Ships/Electric-Ships-Office/>



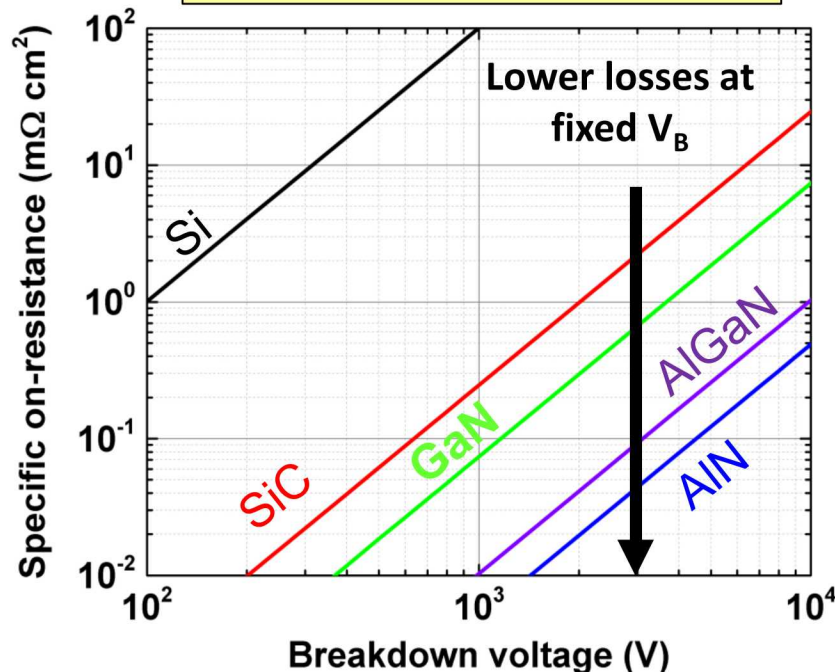
https://afdc.energy.gov/vehicles/electric_basics_ev.html

- Mechanical CBs are **bulky** and **slow**
- Solid State CBs promise faster response times, **smaller form factors**
- Current DC CB available for low voltage and low power applications

Approach

Project Objectives

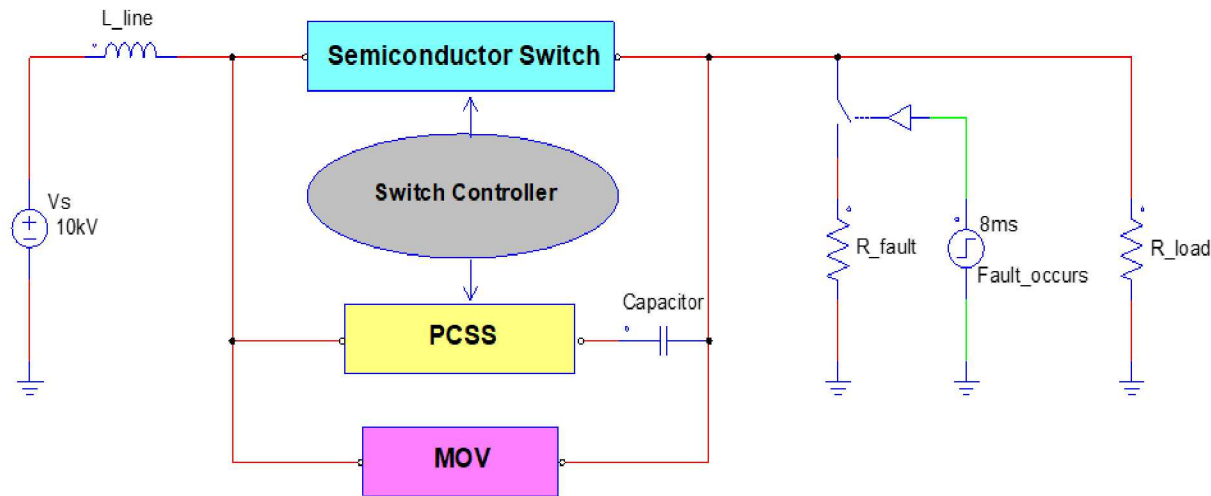
Vertical “unipolar” FOM
 $= V_B^2 / R_{on,sp} = \epsilon \mu_n E_C^3 / 4$



- ▶ Wide bandgap semiconductors (SiC, GaN) enable Solid State CB technologies
 - Lower switching losses
 - Higher power density
- ▶ Our Approach: SiC power electronics + Optically triggered GaN-based switch to enable DC CB
 - **SiC power devices with novel circuit architectures**
 - **GaN-based Photoconductive Semiconductor Switch (PCSS)**
 - **Targeting 10 kV/100 A CB performance**

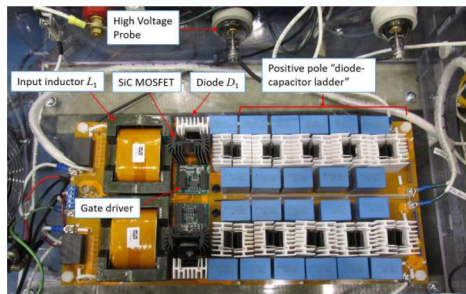
► Goals of project:

- Design and model/simulate Solid State CB
- Develop and analyze 10 kV/100 A GaN PCSS
- Demonstrate DC CB technology
- Develop CB commercialization plan



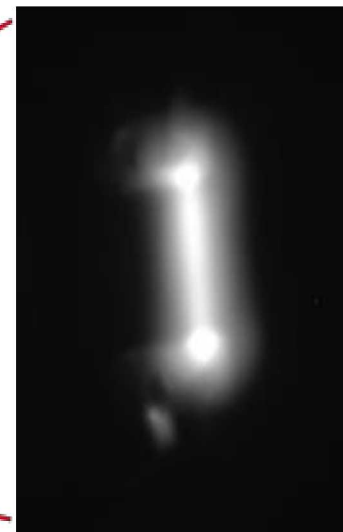
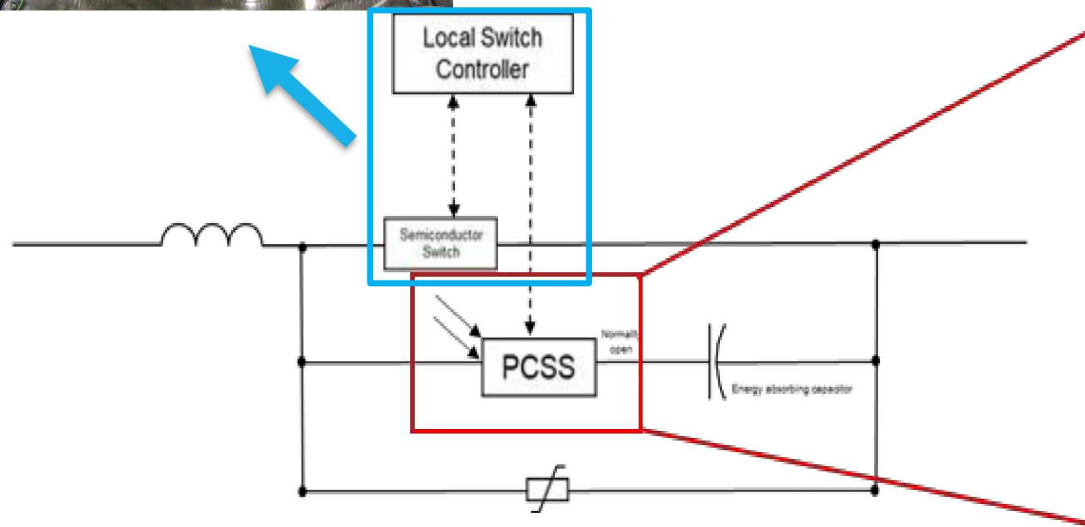
Uniqueness of Approach

Project Objectives



Leverage SNL's experience in novel circuit architecture developed in IDEAS program (Hy-GaN)

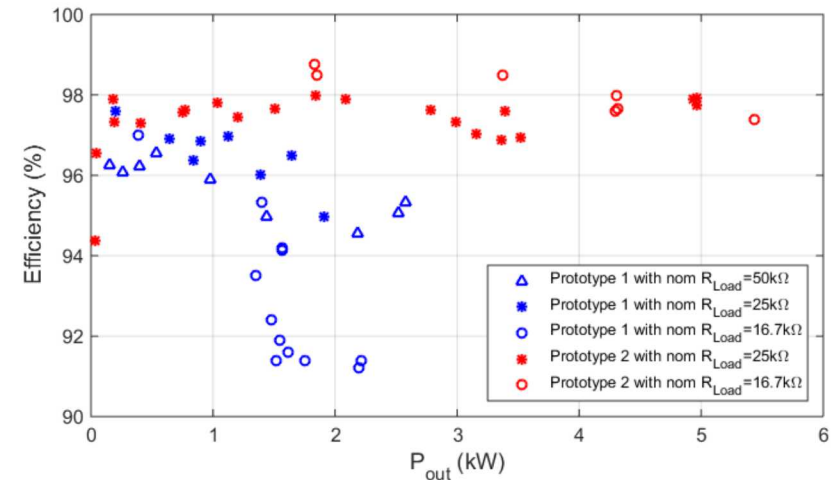
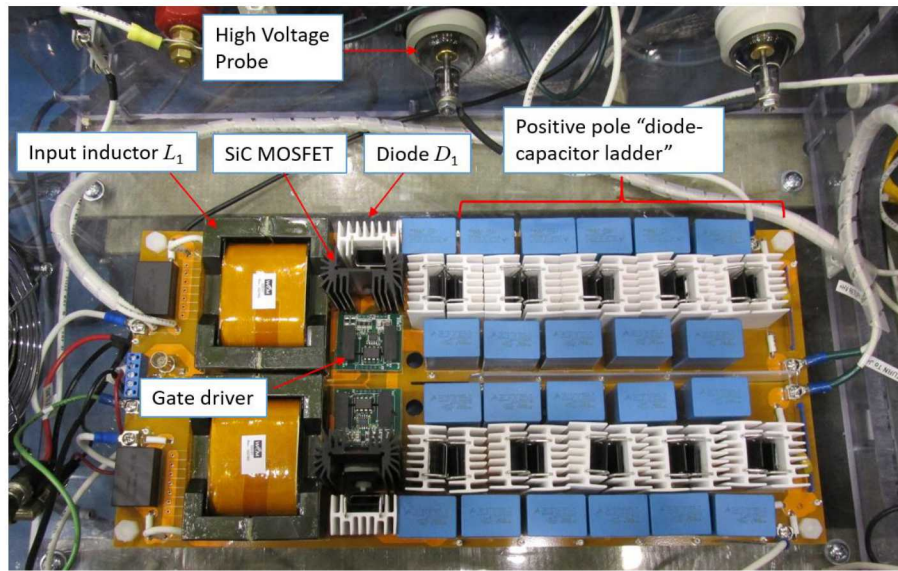
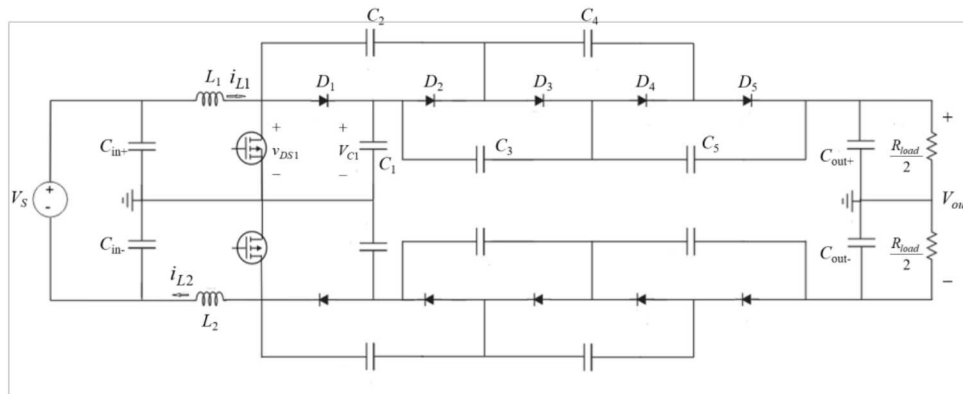
SNL's Lateral GaN PCSS Developed in IDEAS program (GaN PCSS)



- ▶ Normally "On" leg to use SiC MOSFETs with novel circuit architecture
- ▶ Normally "Off" leg to use optically-triggered GaN PCSS (good isolation)
- ▶ Power Dissipation leg to investigate metal oxide varistors, other technologies

Novel Circuit Architectures

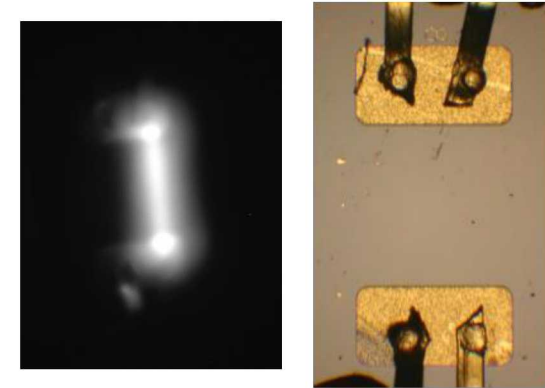
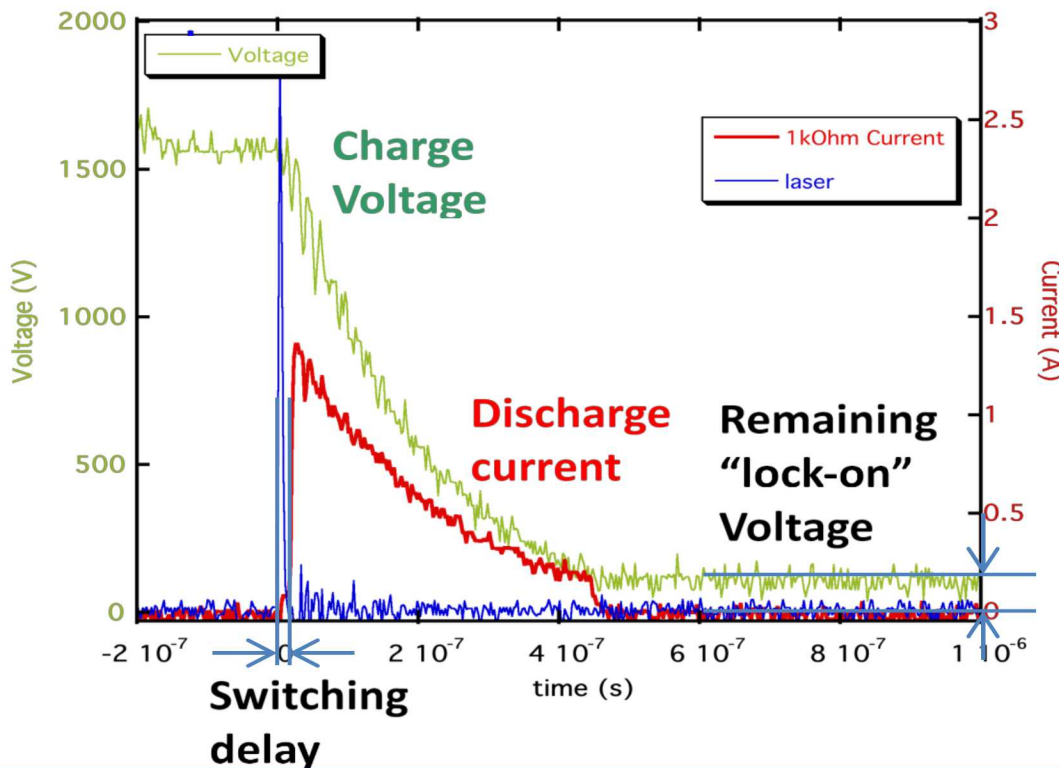
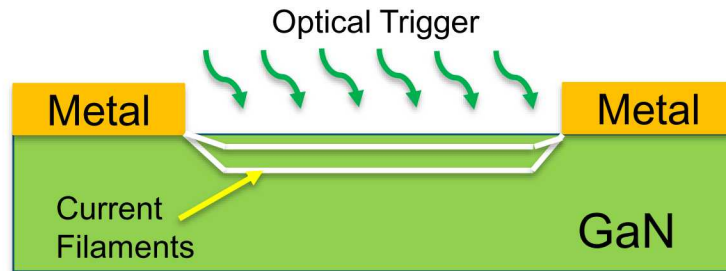
Project Objectives



- Advanced circuit architecture capabilities at SNL
- Demonstrated capability in “Hybrid Switched Capacitor Circuit Development for Use of GaN Diodes in High Gain Step-Up Converters (Hy-GaN) IDEAS program
- Use circuit design and package capabilities toward MVDC CB design

GaN PCSS Technology

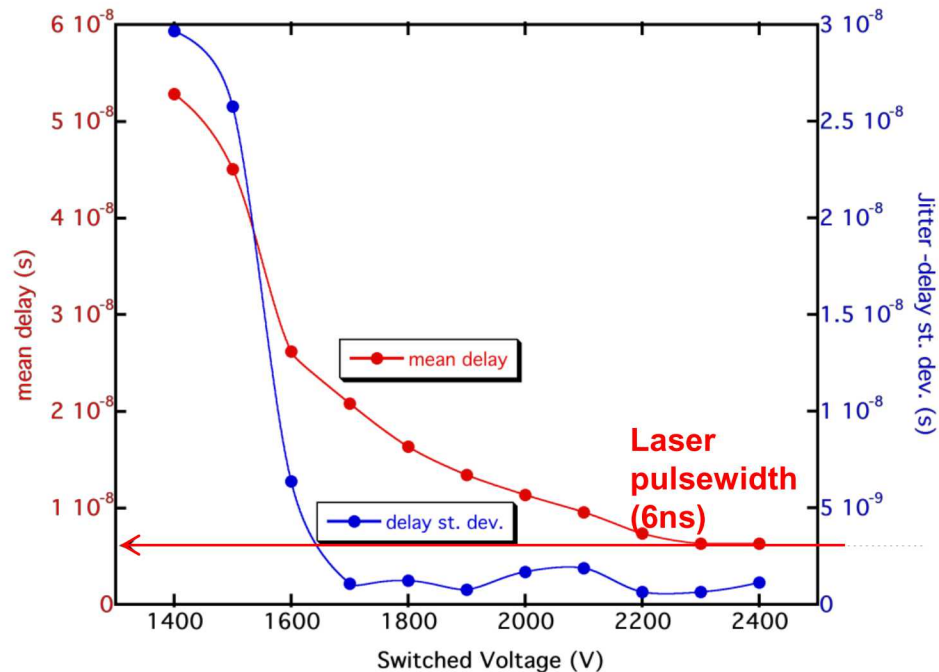
Project Objectives



Filamentary Conduction
35 uJ trigger at 532 nm

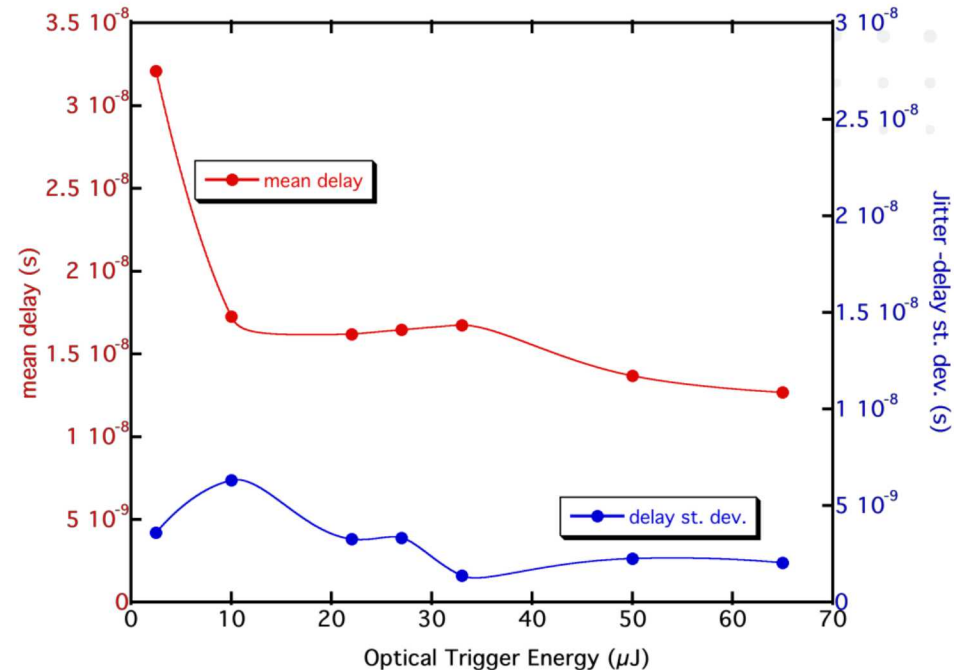
- Long history at SNL for PCSS in other materials (GaAs)
- Demonstrated “high-gain” mode in IDEAS program
- GaN material properties promise high voltage/power switches
- Optical gate control provides isolation

Switching Delay, Jitter Characteristics vs. Applied Voltage



- All data use 50 μ J optical trigger energy, 60 shots per voltage level
- Timing jitter approaches minimum (~ 650 ps) at relatively low voltage (1700V)

Switching Delay, Jitter Characteristics vs. Optical Trigger Energy



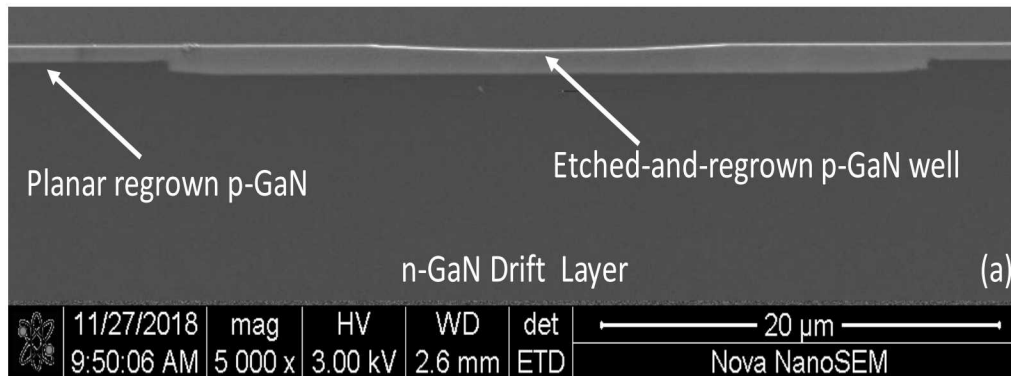
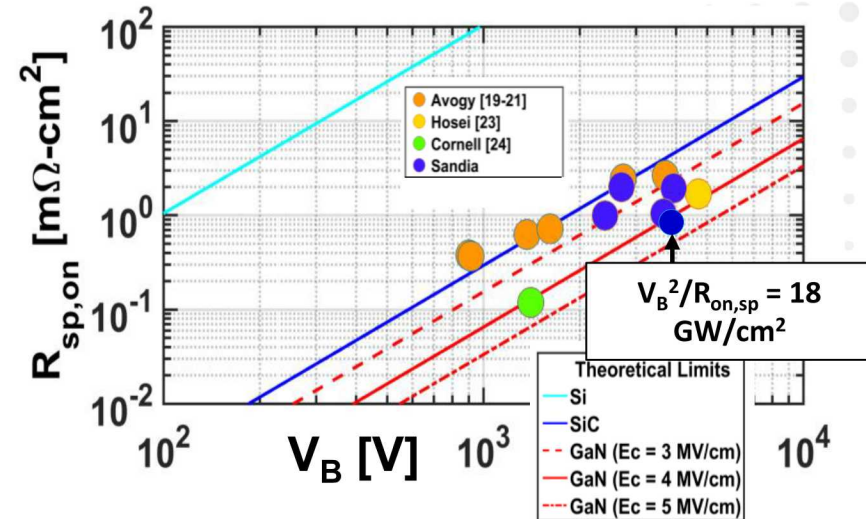
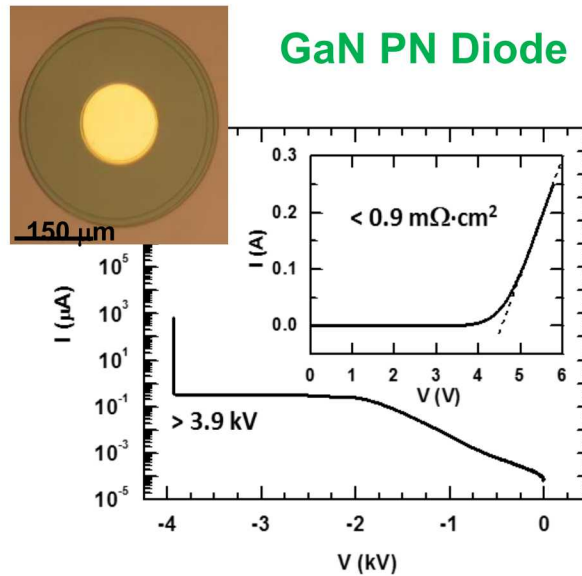
- All data using 2000V applied voltage, 30 shots per optical energy level
- Switching delay and jitter decrease with optical trigger energy

GaN MOCVD Capability

Project Objectives



15+ years in wide band gap materials and device R&D



Developed high-quality etch/regrowth GaN process for selective-area doping.

Etch/regrowth process needed for GaN PCSS devices.

Key Metrics/Outcomes

Project Objectives

Category	Key CB Metrics
Rated Voltage	10 kV DC
Power	1 MW (100 A at 10 kV)
Efficiency	99.97%
Response Time	< 500 μ s
Lifetime	30,000 cycles, TBC
Nuisance Trips	< 0.1% TBC
Power Density	60 MW/m ³ , TBC
Cooling	Passive

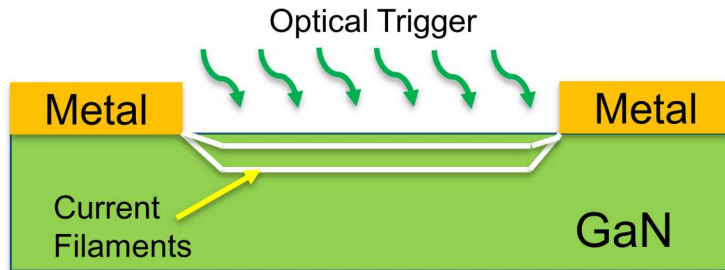
GaN PCSS:

- Evaluate lateral vs. vertical device design/performance
- Develop mechanistic understanding of GaN PCSS device operation
- Evaluate compact optical triggering solutions
- Demonstrate high voltage/high current GaN PCSS

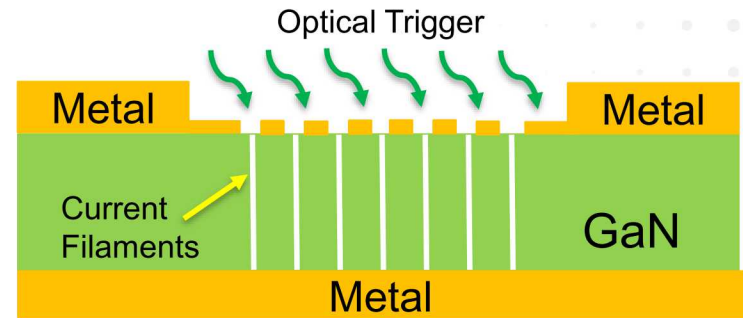
WBS	Description	Year 1			
		Q1	Q2	Q3	Q4
M2.1	Design of normally-on leg of CB.				
M2.2	Design of shunt leg of CB.				
M2.3	Design of normally-off leg of CB.				
M2.4	Demonstration of low-voltage CB operation. 1.2 kV, 10 A, operating speed < 500 μ s.				
M2.5	Develop mechanistic understanding of GaN PCSS devices (model/simulation)				
M3.1	Evaluate vertical GaN PCSS prototypes for high-gain mode operation.				

Biggest challenges revolve around GaN PCSS: Demonstration (Vertical design) and Mechanistic Understanding

Lateral Device Design



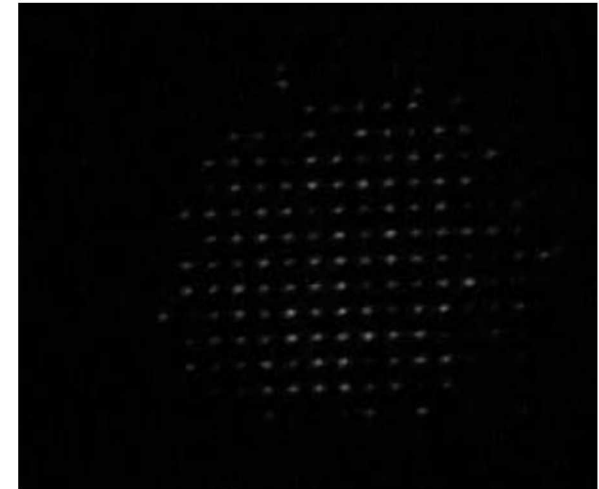
Vertical Device Design



GaAs Vertical PCSS (right)

- ~120 current-sharing filaments visible per shot, changing positions each shot
- Current sharing greatly improves total current-handling and device lifetime
- Vertical design needs to be proven/characterized for GaN materials

Top Image GaAs PCSS



- ▶ Model of GaN PCSS device in high gain mode
- ▶ Evaluation of vertical GaN PCSS device design
- ▶ Gen1 designs for three legs of DC CB
- ▶ Gen2 designs for three legs of DC CB
- ▶ Bench-top Demonstration of low-voltage CB
 - 1.2 kV, 10 A, operating speed $< 500 \mu\text{s}$
- ▶ Will allow for design optimizations and down-select technologies for Gen2 DC CB demonstrations
- ▶ Key Results for next meeting: GaN PCSS device results, results from bench-top demonstration



Greg Pickrell, Principal Investigator, GaN Power Devices



Alan Mar, PCSS Device design/characterization, pulsed power



Emily Schrock, PCSS Device design/characterization, pulsed power



Andy Allerman, GaN MOCVD growth, power devices



Harry Hjalmarson, PCSS Device theory, modeling/simulation



Stan Atcity, Power systems, design optimization



Jason Neely, Power circuit, design optimization, and fabrication



Jack Flicker, Power circuits, simulation, and integration



Bob Kaplar, GaN Power Devices, reliability, project management

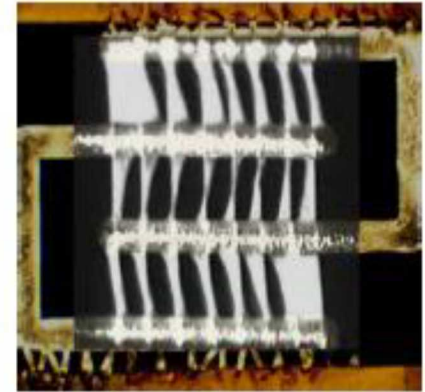
▪ MESA Facility

- GaN Material MOCVD growth and material characterization
- Semiconductor device fabrication
- Material and device defect characterization
- High voltage characterization

MOCVD Reactor



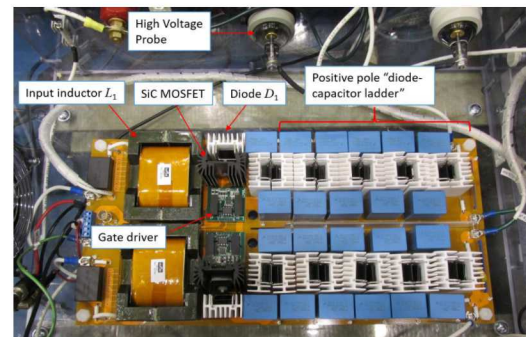
GaAs PCSS



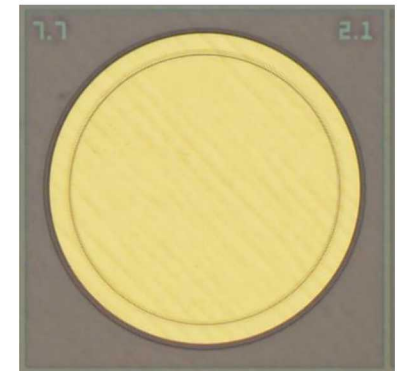
▪ Pulsed Power Laboratories

- PCSS device characterization

Novel Circuit Design



GaN PN Diode

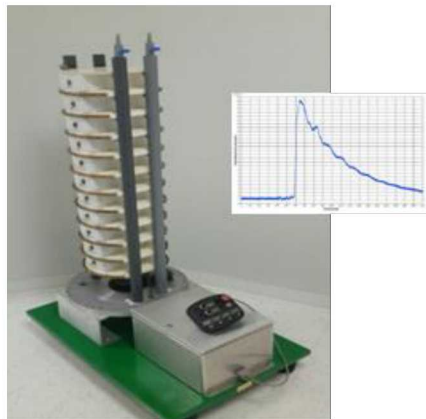


▪ Power Circuit Laboratories

- Design optimization
- Modeling/simulation
- Fabrication/integration
- High voltage characterization



Professor Jane Lehr, Director of UNM's Applied Pulsed Energy, Discharge, and Ionization Center (APERIODIC), high power electromagnetics, pulsed power, high voltage engineering, ultra-fast switching.



APERIODIC Laboratory:

- 1500 sq. ft facility on UNM main campus
- Suite of self-contained and modular pulsed sources
- Portable “Harpo” Marx bank pulsed source (300 kV/400 ns)
– pictured on left
- Self-matched pulser (0.5-40 kV)
- Portable and shielded LabVIEW data acquisition systems

- ▶ As SNL is FFRDC, our primary path for tech to market is licensing
 - Also opportunities for entrepreneurial development
- ▶ Applications in DC Electrical Grid (renewables) and electric vehicles (ship, rail, car) are likely opportunities
- ▶ First actions are to discuss application requirements in several areas with customers:
 - DC power conversion
 - Renewable energy integration into the grid
 - Electric ships

- ▶ Semi-Insulating (SI) GaN wafer sourcing is a concern
 - Limited domestic sources of SI GaN wafers
 - Supplier with advanced maturity are overseas (Poland)
 - Varying synthesis methods with small substrate size
 - Will purchase from multiple vendors to minimize risk

Foreign Supplier #1



Domestic Supplier #1



Foreign Supplier #2

Substrate
quotation and
evaluation
underway

Conclusions

- ▶ Medium Voltage DC CB approach leverages capabilities of Wide Bandgap semiconductors
 - Critical for power density requirements
 - Commercial/R&D SiC power electronics
 - Novel GaN PCSS (optically triggered, fast acting)
- ▶ Team includes expertise and facilities ideal to develop
 - Novel SiC circuit architectures
 - GaN growth by MOCVD
 - Wide bandgap GaN devices
 - High voltage and high speed device/circuit/system characterization